2) Manual-reset input.

memory devices.

Computers Controllers

Intelligent Instruments Critical µP Power Monitoring

period.

accuracy (±2%).

1)

Microprocessor and Non-Volatile Memory Supervisory Circuits

General Description

The MAX792/MAX820 microprocessor (µP) supervisory

circuits provide the most functions for power-supply

and watchdog monitoring in systems without battery

uP reset: Assertion of RESET and RESET outputs dur-

ing power-up, power-down, and brownout condi-

comparator compares V_{CC} to a preset threshold

120mV above the reset threshold; the low-line and reset thresholds can be programmed externally.

tions. RESET is guaranteed valid for V_{CC} down to 1V.

3) Two-stage power-fail warning: A separate low-line

 Watchdog fault output: Assertion of WDO if the watchdog input is not toggled within a preset timeout

 Pulsed watchdog output: Advance warning of impending WDO assertion from watchdog timeout

6) Write protection of CMOS RAM, EEPROM, or other

The MAX792 and MAX820 are identical, except the

MAX820 guarantees higher low-line and reset threshold

Applications

that causes hardware shutdown.

backup. Built-in features include the following:

_Features

- Manual-Reset Input
- ♦ 200ms Power-OK/Reset Time Delay
- Independent Watchdog Timer—Preset or Adjustable
- On-Board Gating of Chip-Enable Signals
- Memory Write-Cycle Completion
- + 10ns (max) Chip-Enable Gate Propagation Delay
- Voltage Monitor for Overvoltage Warning
- ±2% Reset and Low-Line Threshold Accuracy (MAX820, external programming mode)

Ordering Information

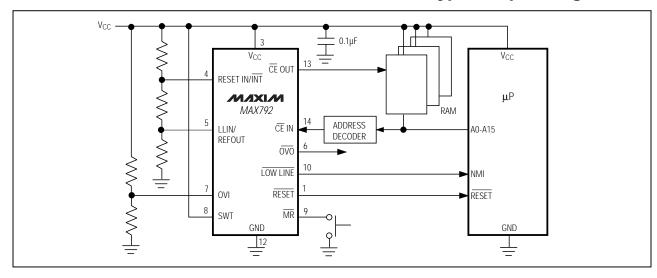
PART**	TEMP. RANGE	PIN-PACKAGE
MAX792_CPE	0°C to +70°C	16 Plastic DIP
MAX792_CSE	0°C to +70°C	16 Narrow SO
MAX792_C/D	0°C to +70°C	Dice*

Ordering Information continued at end of data sheet. * Dice are tested at $T_A = +25$ °C, DC parameters only.

**These parts offer a choice of five different reset threshold voltages. Select the letter corresponding to the desired nominal reset threshold voltage and insert it into the blank to complete the part number.

SUFFIX	RESET THRESHOLD (V)
L	4.62
M	4.37
T	3.06
S	2.91
R	2.61

Typical Operating Circuit



____ Maxim Integrated Products 1

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ABSOLUTE MAXIMUM RATINGS

Input Voltage (with respect to GND)

V _{CC}	0.3V to +6V
All Other Inputs	0.3V to (V _{CC} + 0.3V)
Input Current	
GND	25mA
All Other Outputs	25mA
Continuous Power Dissipation ($T_A = + \overline{A}$	
Plastic DIP (derate 10.53mW/°C abc	ve +70°C)842mW
Narrow SO (derate 9.52mW/°C abov	re +70°C)762mW
CERDIP (derate 10.00mW/°C above	+70°C)800mW

Operating Temperature Ranges:

MAX792_C/MAX820_C	0°C to +70°C
MAX792_E/MAX820_E	-40°C to +85°C
MAX792_MJE/MAX820_MJE	55°C to +125°C
Storage Temperature Range	65°C to +160°C
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = 2.65V to 5.5V, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
Operating Voltage Range		2.65			V	
Supply Current			70	150	μA	
RESET COMPARATOR	1	1				
	MAX792L, MAX820L	4.50	4.62	4.75	-	
	MAX792M, MAX820M	4.25	4.37	4.50		
	MAX792R, MAX820R	2.55	2.61	2.70	-	
	MAX792S, MAX820S	2.85	2.91	3.00	-	
Reset Threshold Voltage— Internal Threshold Mode	MAX792T, MAX820T	3.00	3.06	3.15	V	
(V _{TH})	MAX820L, $T_A = +25^{\circ}C$, V _{CC} falling	4.55		4.70	v	
	MAX820M, $T_A = +25^{\circ}C$, V_{CC} falling	4.30		4.45		
	MAX820R, $T_A = +25^{\circ}C$, V _{CC} falling (Note 1)	2.55		2.66	-	
	MAX820S, $T_A = +25^{\circ}C$, V_{CC} falling	2.85		2.96		
	MAX820T, $T_A = +25^{\circ}C$, V _{CC} falling	3.00		3.11		
Reset Threshold Voltage	MAX792, $V_{CC} = 5V$ or $V_{CC} = 3V$	1.25	1.30	1.35	- V	
External Threshold Mode (V _{TH})	MAX820, $V_{CC} = 5V$ or $V_{CC} = 3V$	1.274	1.30	1.326		
RESET IN/INT Mode Threshold (Note 2)	Internal threshold mode			60	mV	
RESET IN/INT Leakage Current			±0.01	±25	nA	
Reset Threshold Hysteresis		C	0.016 x V _T	Н	V	
Reset Comparator Delay	V _{CC} falling		70		μs	
Reset Active Timeout Period	V _{CC} rising	140	200	280	ms	
	$I_{SINK} = 50\mu A$, $V_{CC} = 1V$, V_{CC} falling		0.01	0.3	V	
	I _{SINK} = 1.6mA		0.1	0.4		
RESET Output Voltage	Isource = 1mA	V _{CC} - 1				
	ISOURCE = 100µA	V _{CC} - 0.5				
	I _{SINK} = 1.6mA		0.1	0.4		
RESET Output Voltage	I _{SOURCE} = 1mA	V _{CC} - 1			V	
	ISOURCE = 100µA	V _{CC} - 0.5]	

ELECTRICAL CHARACTERISTICS (continued) ($V_{CC} = 2.65V$ to 5.5V, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS	
LOW-LINE COMPARATOR			1				
Low-Line Threshold Voltage	MAX792/MAX820L/M		50	120	210		
(Internal Threshold Mode)—VTH	MAX792/MAX820R/S/T		40	100	210	— mV	
Low-Line Threshold Voltage	MAX792, $V_{CC} = 5V \text{ OR } V_{CC}$	c = 3V	1.25	1.30	1.35		
(External Programming Mode)	MAX820, $V_{CC} = 5V \text{ OR } V_{CC}$	c = 3V	1.274	1.30	1.326	- V	
Low-Line Hysteresis (Internal Threshold Mode)				20		mV	
LLIN/REFOUT Leakage Current External Programming Mode				±0.01	±25	nA	
Low-Line Comparator Delay	V _{CC} falling			450		μs	
LOWLINE Voltage	I _{SINK} = 3.2mA				0.4	V	
LOWLINE Voltage	$I_{SOURCE} = 1 \mu A$		V _{CC} - 1			V	
LOWLINE Short-Circuit Current	Output source current, V _{CC}	: = 5.5V		10	50	μΑ	
WATCHDOG FUNCTION							
	SWT connected to V_{CC} , $V_{CC} = 5V$		1.00	1.60	2.25	sec	
	SWT connected to V_{CC} , $V_{CC} = 3V$		1.00	1.60	2.25	300	
Watchdog Timeout Period	4.7nF capacitor connected from SWT to GND, $V_{CC} = 3V$			70			
	4.7nF capacitor connected from SWT to GND, V _{CC} = 5V			100		– ms	
Watchdog Ipput Dulco Width		$V_{CC} = 5V$ 100			nc		
Watchdog Input Pulse Width	$V_{IL} = 0V, V_{IH} = V_{CC}$	$V_{CC} = 3V$	300			ns ns	
	$I_{SINK} = 50 \mu A$, $V_{CC} = 1V$, V_{CC}	C falling		0.01	0.30		
WDO Output Voltage	I _{SINK} = 1.6mA			0.1	0.4	v	
WDO Odipat Voltage	I _{SOURCE} = 1mA		V _{CC} - 1				
	Isource = 100µA		V _{CC} - 0.5				
WDPO to WDO Delay				70		ns	
WDPO Duration			0.5	1.7	6.0	ms	
	$I_{SINK} = 50\mu A$, $V_{CC} = 1V$, V_{CC} falling			0.01	0.3	V	
WDPO Output Voltage	I _{SINK} = 1.6mA			0.1	0.4		
	I _{SOURCE} = 1mA		V _{CC} - 1				
	I _{SOURCE} = 100µA		V _{CC} - 0.5				
WDI Threshold Voltage	$V_{CC} = 4.25V$	ViH	0.75 x V _{CC}			V	
		VIL			0.8		
WET INTESHOLD VOILage	Vcc = 2.55V	VIH	0.9 x V _{CC}				
	VUU - 2.00V	VIL			0.2		
WDI Input Current					±1	μΑ	

MAX792/MAX820

ELECTRICAL CHARACTERISTICS (continued)

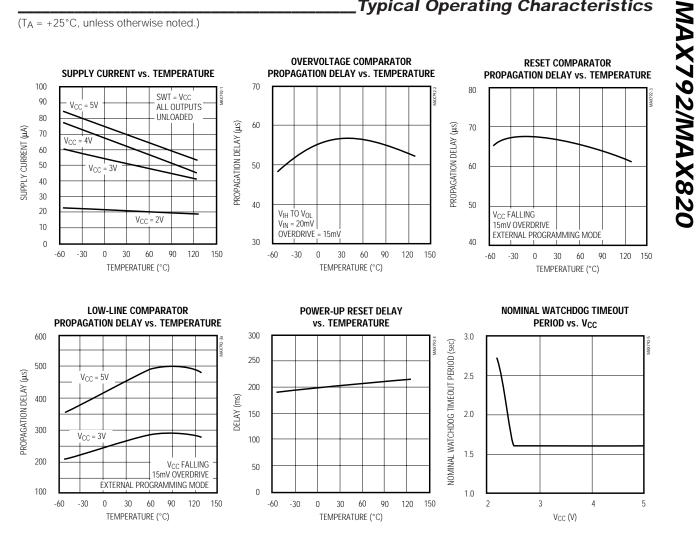
 $(V_{CC} = 2.65V \text{ to } 5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS	
OVERVOLTAGE COMPARATO	R						
OVI Input Threshold	$V_{CC} = 5V \text{ or } V_{CC} = 3V$		1.25	1.30	1.35	V	
OVI Leakage Current				±0.01	±25	nA	
	I _{SINK} = 3.2mA				0.4	14	
OVO Output Voltage	Isource = 1µA		Vcc - 1			- V	
OVO Short-Circuit Current	Output source current, $V_{CC} = 5.5$	ōV		10	50	μΑ	
	$V_{OD} = 100 \text{mV}$, OVI rising			13			
OVI to OVO Delay	$V_{OD} = 100 \text{mV}$, OVI falling			55		– μs	
CHIP-ENABLE GATING	•						
	$V_{CC} = 4.25V$	Vih	0.75 x V _{CC}				
CE IN Threshold Voltage	$V_{CC} = 4.25V$	VIL			0.8	V	
OE IN Threshold Voltage	V _{CC} = 2.55V	VIH	0.75 x V _{CC}				
		VIL			0.2		
CE IN Leakage Current	Disabled mode			±0.005	±1	μΑ	
$\overline{\text{CE}}$ IN to $\overline{\text{CE}}$ OUT Resistance	Enabled mode	$V_{CC} = 5V$		75	150	- Ω	
		$V_{CC} = 3V$		150	300		
CE OUT Short-Circuit Current	Disabled mode, $\overline{CE}_{OUT} = 0V$	$V_{CC} = 5V$	0.5		2.5	mA	
		$V_{CC} = 3V$	0.05	0.2	0.4		
Chip-Enable Propagation Delay	50Ω source impedance driver,	$V_{CC} = 5V$		6	10	ns	
(Note 3)	$C_{LOAD} = 50 pF$	$V_{CC} = 3V$		8	13		
Chip-Enable Output Voltage High (Reset Active)	$I_{OUT} = -100\mu A$		V _{CC} - 1			V	
a .	$I_{OUT} = 10\mu A$		Vcc - 0.5	1 -			
Reset Active to CE OUT High	V _{CC} falling			15		μs	
			2E			110	
MR Minimum Pulse Width			25			μs	
MR to RESET Propagation Delay				12		μs	
MR Threshold Range			1.1	1.3	1.5	V	
MR Pull-Up Current	$\overline{MR} = 0V$	$V_{CC} = 4.25V$ to V_{CC} = 5.5V	5	23	80	μA	
	$V_{CC} = 2.5 V$		1			7	

Note 1: The minimum operating voltage is 2.65V; however, the device is guaranteed to operate down to its preset reset threshold.
Note 2: Pulling RESET IN/INT below 60mV selects internal threshold mode and connects the internal voltage divider to the reset and low-line comparators. External programming mode allows an external resistor divider to set the low-line and reset thresholds (see Figure 4).

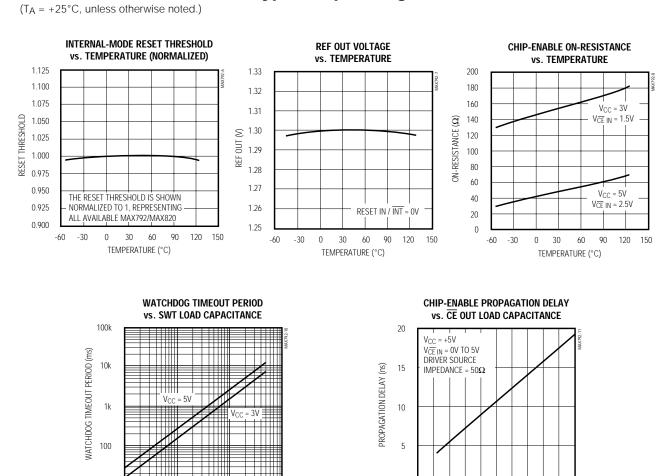
Note 3: The Chip-Enable Propagation delay is measured from the 50% point at \overline{CE} IN to the 50% point at \overline{CE} OUT.

Typical Operating Characteristics



 $(T_A = +25^{\circ}C, unless otherwise noted.)$

M/X/M



0

0 25

50 75 100 125 150 175 200 225 250

CLOAD (pF)

Typical Operating Characteristics (continued)

10

1n

10n

C_{SWT} (F)

100n

1m

MAX792/MAX820

_Pin Description

PIN	NAME	FUNCTION	
1	RESET	Active-Low Reset Output goes low whenever V_{CC} falls below the reset threshold in internal threshold programming mode, or RESET IN falls below 1.30V in external threshold programming mode. RESET remains low for 200ms typ after the threshold is exceeded on power-up.	
2	RESET	Reset is the inverse of RESET.	
3	V _{CC}	Input Supply Voltage	
4	RESET IN/INT	Reset-Input/Internal-Mode Select. Connect this input to GND to select internal threshold mode. Select external programming mode by pulling this input 600mV or higher through an external voltage divider.	
5	LLIN/REF OUT	Low-Line Input/Reference Output connects directly to the low-line comparator in external program- ming mode (RESET IN/INT \ge 600mV). Connects directly to the internal 1.30V reference in internal threshold mode (RESET IN/INT \le 60mV).	
6	OVO	Overvoltage Comparator Output goes low when OVI is greater than 1.30V. This is an uncommitted comparator and has no effect on any other internal circuitry.	
7	OVI	Inverting Input to the Overvoltage Comparator. When OVI is greater than 1.30V, $\overline{\text{OVO}}$ goes low. Connect OVI to GND or V _{CC} when not used.	
8	SWT	Set Watchdog-Timeout Input. Connect this input to V _{CC} to select the default 1.6sec watchdog timeout period. Connect a capacitor between this input and GND to select another watchdog timeout period. Watchdog timeout period = k x (capacitor value in nF)mV, where k = 27 for V _{CC} = 5V and k = 16.2 for V _{CC} = 3V. If the watchdog function is unused, connect SWT to V _C	
9	MR	Manual-Reset Input. This input can be tied to an external momentary pushbutton switch, or to a logic gate output. Internally pulled up to V_{CC} .	
10	LOW LINE	Low-Line Output. LOW LINE goes low 120mV above the reset threshold in internal threshold mode, or when LLIN/REFOUT goes below 1.30V in external programming mode.	
11	WDI	Watchdog Input. If WDI remains either high or low for longer than the watchdog timeout period, \overline{WDPO} pulses low and \overline{WDO} goes low. \overline{WDO} remains low until the next transition at WDI. Connect to GND or V _{CC} if unused.	
12	GND	Ground	
13	CE OUT	Chip-Enable Output. CE OUT goes low only when CE IN is low and reset is not asserted. If CE IN is low when reset is asserted, CE OUT will stay low for 15µs or until CE IN goes high, whichever occurs first.	
14	CE IN	Chip-Enable Input—the input to the chip-enable transmission gate. Connect to GND or V _{CC} if not used.	
15	WDO	Watchdog Output. WDO goes low if WDI remains either high or low longer than the watchdog time- out period. WDO returns high on the next transition at WDI.	
16	WDPO	Watchdog-Pulse Output. Upon the absence of a transition at WDI, WDPO will pulse low for a mini- mum of 500µs. WDPO precedes WDO by typically 70ns.	



Detailed Description

Manual-Reset Input

Many μ P-based products require manual-reset capability, allowing the operator to initiate a reset. The manual/external-reset input (MR) can connect directly to a switch without an external pull-up resistor or debouncing network. MR internally connects to a 1.30V comparator, and has a high-impedance pull-up to V_{CC}, as shown in Figure 1. The propagation delay from asserting MR to reset asserted is typically 12µs. Pulsing MR low for a minimum of 25µs asserts the reset function (see *Reset Function* section). The reset output remains active as long as MR is held low, and the reset timeout period begins after MR returns high (Figure 2). To provide extra noise immunity in high-noise environments, pull MR up to V_{CC} with a 100k Ω resistor.

Use MR as either a digital logic input or as a second lowline comparator. Normal TTL/CMOS levels can be wire-OR connected via pull-down diodes (Figure 3), and open-drain/collector outputs can be wire-ORed directly.

Monitoring the Regulated Supply

The MAX792/MAX820 offer two modes for monitoring the regulated supply and providing reset and non-maskable interrupt (NMI) signals to the μ P: internal threshold mode uses the factory preset low-line and reset thresholds, and external programming mode allows the low-line and reset thresholds to be programmed externally using a resistor voltage divider (Figure 4).

Internal Threshold Mode

Connecting the reset-input/internal-mode select pin (RESET IN/INT) to ground selects internal threshold mode (Figure 4a). In this mode, the low-line and reset thresholds are factory preset by an internal voltage divider (Figure 1) to the threshold voltages specified in the *Electrical Characteristics* (Reset Threshold Voltage and Low-Line Threshold Voltage). Connect the low-line output (LOWLINE) to the μ P NMI pin, and connect the active-high reset output (RESET) or active-low reset output (RESET) to the μ P reset input pin.

Additionally, the low-line input/reference-output pin (LLIN/REFOUT) connects to the internal 1.30V reference in internal threshold mode. Buffer LLIN/REFOUT with a high-impedance buffer to use it with external circuitry. In this mode, when V_{CC} is falling, LOWLINE is guaranteed to be asserted prior to reset assertion.

External Programming Mode

Connecting RESET IN/INT to a voltage above 600mV selects external programming mode. In this mode, the low-line and reset comparators disconnect from the internal voltage divider and connect to LLIN/REFOUT and RESET IN/INT, respectively (Figure 1). This mode allows flexibility in determining where in the operating voltage range the NMI and reset are generated. Set the low-line and reset thresholds with an external resistor divider, as in Figure 4b or Figure 4c. RESET typically remains valid for V_{CC} down to 2.5V; RESET is guaranteed to be valid with V_{CC} down to 1V.

Calculate the values for the resistor voltage divider in Figure 4b using the following equations:

1) R3 = $(1.30 \times V_{CC} \text{ MAX})/(V_{LOW LINE} \times I_{MAX})$

3) $R1 = (V_{CC} MAX/I_{MAX}) - (R2 + R3).$

First choose the desired maximum current through the voltage divider (I_{MAX}) when V_{CC} is at its highest (V_{CC} MAX). There are two things to consider here. First, I_{MAX} contributes to the overall supply current for the circuit, so you would generally make it as small as possible. Second, I_{MAX} cannot be too small or leakage currents will adversely affect the programmed threshold voltages; 5µA is often appropriate. Determine R3 after you have chosen I_{MAX} . Use the value for R3 to determine R2, then use both R2 and R3 to determine R1.

For example, to program a 4.75V low-line threshold and a 4.4V reset threshold, first choose I_{MAX} to be 5µA when V_{CC} = 5.5V and substitute into equation 1.

 $R3 = (1.30 \times 5.5)/(4.75 \times 5E-6) = 301.05k\Omega$

 $\text{301k}\Omega$ is the nearest standard 0.1% value. Substitute into equation 2:

 $R2 = [(1.30 \times 5.5)/(4.4 \times 5E-6)] - 301k\Omega = 23.95k\Omega.$

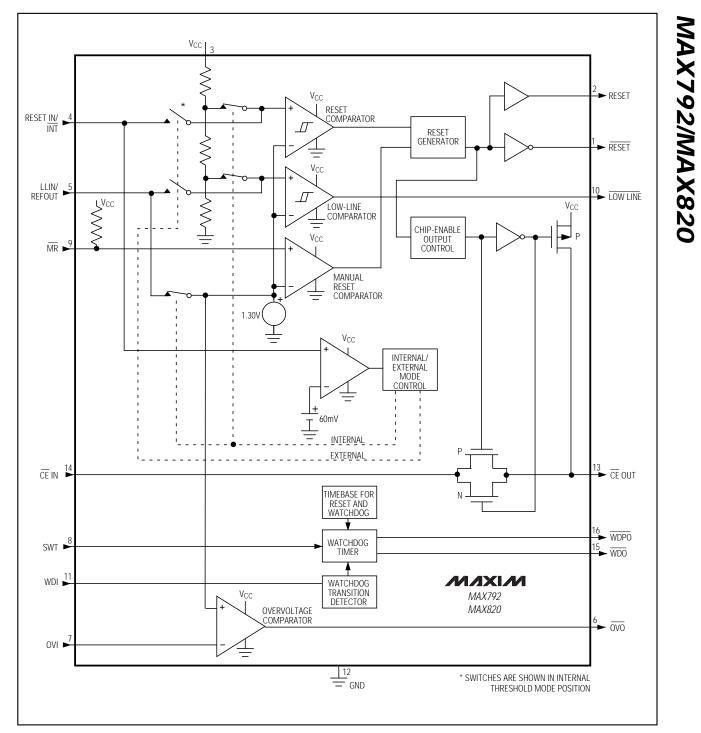
The nearest 0.1% resistor value is 23.7 k $\Omega.$ Finally, substitute into equation 3:

R1 = $(5.5/5E-6) - (23.7k\Omega + 301k\Omega) = 775k\Omega$.

The nearest 0.1% value resistor is $787k\Omega$. Determine the actual low-line threshold by rearranging equation 1 and plugging in the standard resistor values. The actual low-line threshold is 4.75V and the actual reset threshold is 4.40V. An additional resistor allows the MAX792/MAX820 to monitor the unregulated supply and provide an NMI before the regulated supply begins to fall (Figure 4c).

Both of these thresholds will vary from circuit to circuit with resistor tolerance, reference variation, and comparator offset variation. The initial thresholds for each circuit will also vary with temperature due to reference and offset drift. For highest accuracy, use the MAX820.









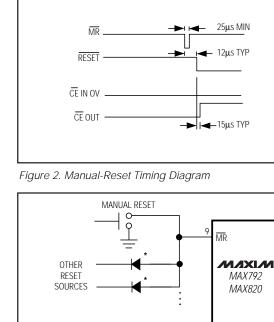


Figure 3. Diode "OR" connections allow multiple reset sources to connect to MR.

* DIODES NOT REQUIRED ON OPEN-DRAIN OUTPUTS

Low-Line Output

In internal threshold mode, the low-line comparator monitors V_{CC} with a threshold voltage typically 120mV above the reset threshold, and with 15mV of hysteresis. For normal operation (V_{CC} above the reset threshold), LOWLINE is pulled to V_{CC} . Use LOWLINE to provide an NMI to the μ P, as described in the previous section, when V_{CC} begins to fall (Figure 4).

Reset Function

The MAX792/MAX820 provide both RESET and RESET outputs. The RESET and RESET outputs ensure that the μ P powers up in a known state, and prevent code-execution errors during power-up, power-down, or brownout conditions.

The reset function will be asserted during the following conditions:

- 1) V_{CC} less than the programmed reset threshold.
- 2) MR less than 1.30V typ.
- 3) Reset remains asserted for 200ms typ after V_{CC} rises above the reset threshold or after \overline{MR} has exceeded 1.30V typ.

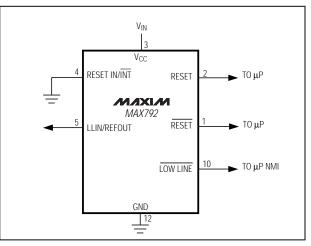


Figure 4a. Connection for Internal Threshold Mode

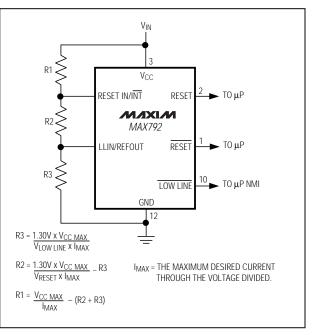


Figure 4b. Connection for External Threshold Programming Mode

When reset is asserted, all the internal counters are reset, the watchdog output (WDO) and watchdog-pulse output (WDPO) are set high, and the set watchdog-time-out input (SWT) is set to (V_{CC} - 0.6V) if it is not already connected to V_{CC} (for internal timeouts). The chipenable transmission gate is also disabled while reset is asserted; the chip-enable input (CE IN) becomes high impedance and the chip-enable output (CE OUT) is pulled up to V_{CC}.



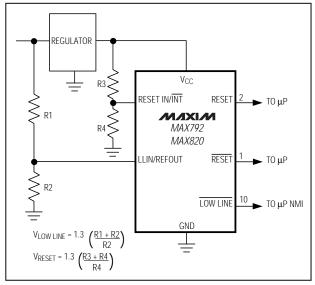


Figure 4c. Alternative Connection for External Programming Mode

Reset Outputs (RESET and RESET)

The RESET output is active low and typically sinks 1.6mA at 0.1V. When deasserted, RESET sources 1.6mA at typically V_{CC} - 1.5V. The RESET output is the inverse of RESET. RESET is guaranteed to be valid down to V_{CC} = 1V, and an external 10k Ω pull-down resistor on RESET ensures that it will be valid with V_{CC} down to GND (Figure 5). As V_{CC} goes below 1V, the gate drive to the RESET output switch reduces accordingly, increasing the r_{DS(ON)} and the saturation voltage. The 10k Ω pull-down resistor ensures that the parallel combination of switch plus resistor will be around 10k Ω and the saturation voltage will be below 0.4V while sinking 40µA. When using an external pull-down resistor of 10k Ω , the high state for the RESET output with V_{CC} = 4.75V is typically 4.60V.

Overvoltage Comparator

The overvoltage comparator is an uncommitted comparator that has no effect on the operation of other chip functions. Use this input to provide overvoltage indication by connecting a voltage divider from the input supply, as in Figure 6.

Connect OVI to ground if the overvoltage function is not used. $\overline{\text{OVO}}$ goes low when OVI goes above 1.30V. With OVI below 1.30V, $\overline{\text{OVO}}$ is actively pulled to V_{CC} and can source1µA.

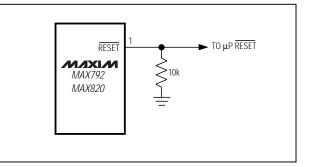


Figure 5. Adding an external pull-down resistor ensures $\overrightarrow{\text{RESET}}$ is valid with V_{CC} down to GND.

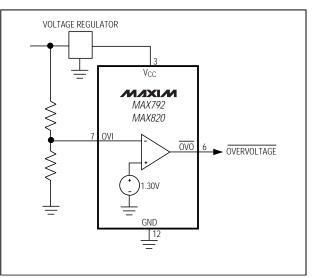


Figure 6. Detecting an Overvoltage Condition

Watchdog Function

The watchdog monitors μ P activity via the watchdog input (WDI). If the μ P becomes inactive, WDO and WDPO are asserted. To use the watchdog function, connect WDI to a μ P bus line or I/O line. If WDI remains high or low for longer than the watchdog timeout period (1.6sec nominal), WDPO and WDO are asserted, indicating a software fault condition (see *Watchdog-Pulse Output* and *Watchdog Output* sections).

Watchdog Input

If the watchdog function is unused, connect WDI to V_{CC} or GND. A change of state (high-to-low, low-to-high, or a minimum 100ns pulse) at WDI during the watchdog period resets the watchdog timer. The watchdog timer

MAX792/MAX820

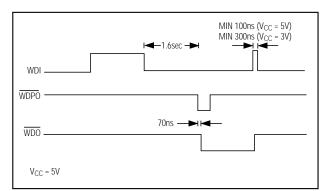


Figure 7. WDI, WDO and WDPO Timing Diagram

default is 1.6sec. Select alternative timeout periods by connecting an external capacitor from SWT to GND (see *Selecting an Alternative Watchdog Timeout* section). When V_{CC} is below the reset threshold, the watchdog function is disabled.

Watchdog Output

WDO remains high if there is a transition or pulse at WDI during the watchdog timeout period. The watchdog function is disabled and \overline{WDO} is a logic high when V_{CC} is below the reset threshold. If a system reset is desired on every watchdog fault, simply diode-OR connect WDO to \overline{MR} (Figure 8). When a watchdog fault occurs in this mode, WDO goes low, pulling MR low and causing a reset pulse to be issued. As soon as reset is asserted, the watchdog timer clears and WDO goes high. With WDO connected to MR, a continuous high or low on WDI will cause 200ms reset pulses to be issued every 1.6sec (SWT connected to V_{CC}). When reset is not asserted, if no transition occurs at WDI during the watchdog timeout period, WDO goes low 70ns after the falling edge of WDPO and remains low until the next transition at WDI (Figure 7). A single additional flip-flop can force the system into a hardware shutdown if there are two successive watchdog faults (Figure 8). When the MAX792/MAX820 are operated from a 5V supply, WDO has a 2 x TTL output characteristic.

Watchdog-Pulse Output

As described in the preceding section, WDPO can be used as the clock input to an external D flip-flop. Upon the absence of a watchdog edge or pulse at WDI at the end of a watchdog timeout period, WDPO will pulse low for 1.7ms. The falling edge of WDPO precedes WDO by 70ns. Since WDO is high when WDPO goes low, the flipflop's Q output remains high after WDO goes low (Figure 8). If the watchdog timer is not reset by a transition at

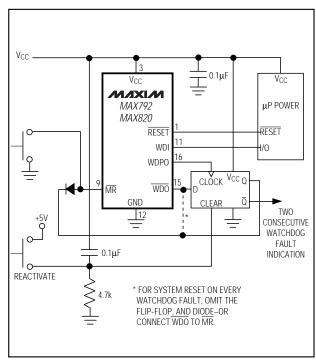


Figure 8. Two consecutive watchdog faults latch the system in reset.

WDI, \overline{WDO} remains low and the next \overline{WDPO} following a second watchdog timeout period clocks a logic low to the Q output, pulling \overline{MR} low and causing the MAX792/MAX820 latch in reset. If the watchdog timer is reset by a transition at WDI, \overline{WDO} will go high and the flip-flop's Q output will remain high. Thus a system shutdown is only caused by two successive watchdog faults.

Selecting an Alternative Watchdog Timeout Period

The SWT input controls the watchdog timeout period. Connecting SWT to V_{CC} selects the internal 1.6sec watchdog timeout period. Select an alternative watchdog timeout period by connecting a capacitor between SWT and GND. Do not leave SWT floating and do not connect it to ground. The following formula determines the watchdog timeout period:

Watchdog Timeout Period =

k x (capacitor value in nF)ms

where k = 27 for V_{CC} = 3V, and k = 16.2 for V_{CC} = 5V.

This applies for capacitor values in excess of 4.7nF. If the watchdog function is unused, connect SWT to V_{CC} .



Chip-Enable Signal Gating

The MAX792/MAX820 provide internal gating of chipenable (CE) signals, which prevents erroneous data from corrupting CMOS RAM in the event of an undervoltage condition. The MAX792/MAX820 use a series transmission gate from CE IN to CE OUT (Figure 1).

During normal operation (reset not asserted), the CE transmission gate is enabled and passes all CE transitions. When reset is asserted, this path becomes disabled, preventing erroneous data from corrupting the CMOS RAM. The 10ns max CE propagation delay from CE IN to CE OUT enables the MAX792/MAX820 to be used with most μ Ps. If CE IN is low when reset asserts, CE OUT remains low for a short period to permit completion of the current write cycle.

Chip-Enable Input

The CE transmission gate is disabled and $\overline{\text{CE}}$ IN is high impedance (disabled mode) while reset is asserted.

During a power-down sequence when V_{CC} passes the reset threshold, the CE transmission gate disables and \overline{CE} IN immediately becomes high impedance if the voltage at \overline{CE} IN is high. If \overline{CE} IN is low when reset is asserted, the CE transmission gate will disable at the moment \overline{CE} IN goes high or 15µs after reset is asserted, whichever occurs first (Figure 9). This permits the current write cycle to complete during power-down.

During a power-up sequence, the CE transmission gate remains disabled and \overline{CE} IN remains high impedance regardless of \overline{CE} IN activity, until reset is deasserted following the reset timeout period.

While disabled, \overline{CE} IN is high impedance. When the CE transmission gate is enabled, the impedance of \overline{CE} IN will appear as a 75 Ω (V_{CC} = 5V) resistor in series with the load at \overline{CE} OUT.

The propagation delay through the CE transmission gate depends on V_{CC} , the source impedance of the drive connected to CE IN, and the loading on CE OUT (see the Chip-Enable Propagation Delay vs. CE OUT Load Capacitance graph in the *Typical Operating Characteristics*). The CE propagation delay is production tested from the 50% point on CE IN to the 50% point on CE OUT using a 50 Ω driver and 50pF of load capacitance (Figure 10). For minimum propagation delay, minimize the capacitive load at CE OUT, and use a low-output-impedance driver.

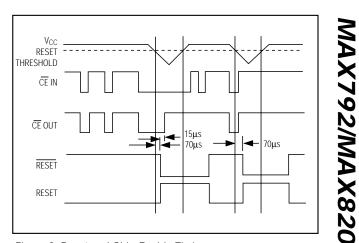


Figure 9. Reset and Chip-Enable Timing

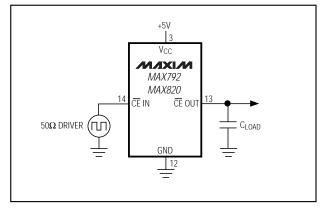


Figure 10. CE Propagation Delay Test Circuit

Chip-Enable Output

When the CE transmission gate is enabled, the impedance of \overline{CE} OUT is equivalent to 75Ω in series with the source driving \overline{CE} IN. In the disabled mode, the 75Ω transmission gate is off and an active pull-up connects from \overline{CE} OUT to V_{CC}. This source turns off when the transmission gate is enabled.

_Applications Information

Connect a 0.1 μ F ceramic capacitor from V_{CC} to GND, as close to the device pins as possible. This reduces the probability of resets due to high-frequency power-supply transients. In a high-noise environment, additional bypass capacitance from V_{CC} to ground may be required. If long leads connect to the chip inputs, ensure that these lines are free from ringing, etc., which would forward bias the chip's protection diodes.

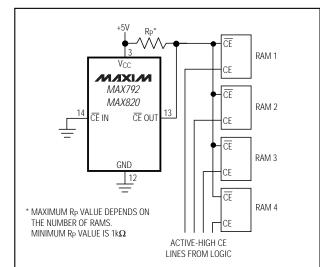


Figure 11. Alternate CE Gating

Alternative Chip-Enable Gating

Using memory devices with both CE and \overline{CE} inputs allows the MAX792/MAX820 CE propagation delay to be bypassed. To do this, connect \overline{CE} IN to ground, pull up CE OUT to V_{CC}, and connect \overline{CE} OUT to the \overline{CE} input of each memory device (Figure 11). The CE input of each memory device then connects directly to the chip-select logic, which does not have to be gated by the MAX792/MAX820.

Interfacing to µPs with Bidirectional Reset Inputs

 $\label{eq:massive} \begin{array}{l} \mu \text{Ps} \text{ with bidirectional reset pins, such as the Motorola} \\ \underline{68HC11} \text{ series, can contend with the MAX792/MAX820} \\ \hline \textbf{RESET} output. If, for example, the MAX792/MAX820} \\ \hline \textbf{RESET} output is asserted high and the } \mu \text{P} \text{ wants to pull it low, indeterminate logic levels may result. To avoid this, connect a 4.7 k} \\ \hline \textbf{\Omega} \text{ resistor between the MAX792/MAX820} \\ \hline \textbf{RESET} output and the } \mu \text{P} \text{ reset I/O, as in Figure 12.} \\ \hline \textbf{Buffer the MAX792/MAX820} \\ \hline \textbf{RESET} output to other system components.} \end{array}$

Negative-Going V_{CC} Transients

While issuing resets to the μ P during power-up, powerdown, and brownout conditions, these supervisors are relatively immune to short-duration negative-going V_{CC} transients (glitches). It is usually undesirable to reset the μ P when V_{CC} experiences only small glitches.

Figure 13 shows maximum transient duration vs. resetcomparator overdrive, for which reset pulses are **not** generated. The graph was produced using negative-

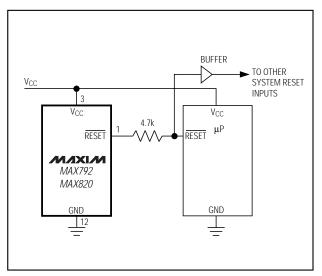


Figure 12. Interfacing to µPs with Bidirectional RESET Pins

going V_{CC} pulses, starting at 5V and ending below the reset threshold by the magnitude indicated (resetcomparator overdrive). The graph shows the maximum pulse width a negative-going V_{CC} transient may typically have without causing a reset pulse to be issued. As the amplitude of the transient increases (i.e., goes farther below the reset threshold), the maximum allowable pulse width decreases. Typically, a V_{CC} transient that goes 100mV below the reset threshold and lasts for 30µs or less will not cause a reset pulse to be issued.

A 100nF bypass capacitor mounted close to the $V_{CC}\xspace$ pin provides additional transient immunity.

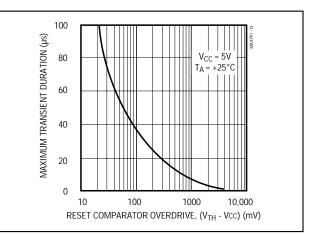


Figure 13. Maximum Transient Duration without Causing a Reset Pulse vs. Reset-Comparator Overdrive

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MAX792/MAX820

_Ordering Information (continued)

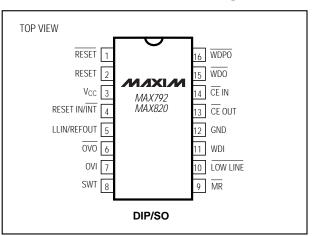
PART**	TEMP. RANGE	PIN-PACKAGE
MAX792_EPE	-40°C to +85°C	16 Plastic DIP
MAX792_ESE	-40°C to +85°C	16 Narrow SO
MAX792_EJE	-40°C to +85°C	16 CERDIP
MAX792_MJE	-55°C to +125°C	16 CERDIP
MAX820_CPE	-0°C to +70°C	16 Plastic DIP
MAX820_CSE	-0°C to +70°C	16 Narrow SO
MAX820_EPE	-40°C to +85°C	16 Plastic DIP
MAX820_ESE	-40°C to +85°C	16 Narrow SO
MAX820_EJE	-40°C to +85°C	16 CERDIP
MAX820_MJE	-55°C to +125°C	16 CERDIP

* Dice are tested at $T_A = +25^{\circ}C$.

**These parts offer a choice of five different reset threshold voltages. Select the letter corresponding to the desired nominal reset threshold voltage and insert it into the blank to complete the part number.

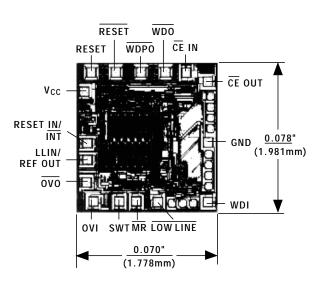
SUFFIX	RESET THRESHOLD (V)
L	4.62
M	4.37
T	3.06
S	2.91
R	2.61

_Pin Configuration



Chip Topography

MAX792/MAX820



TRANSISTOR COUNT: 950 SUBSTRATE CONNECTED TO V_{CC}

Package Information 8888 <u>BBBB</u> 8888 0• -8 Α В - C Δ1
 INCHES
 MILLIMETERS

 MIN
 MAX
 MIN
 MAX

 A
 0.093
 0.104
 2.35
 2.65

 A
 0.093
 0.012
 0.10
 0.30

 B
 0.014
 0.019
 0.35
 0.49

 C
 0.009
 0.010
 1.02
 1.02

 P
 0.050
 1.27
 1.27

 INCHES
 MILLIMETERS

 MIN
 MAX
 MIN
 MAX
 N MS013

 D
 0.398
 0.413
 10.10
 10.50
 16
 AA

 D
 0.447
 0.463
 11.35
 11.75
 18
 AB

 D
 0.4546
 0.512
 12.60
 13.00
 20
 AC

 D
 0.598
 0.614
 15.20
 15.60
 24
 AD
 0.050 0.291 0.299 0.394 0.419 1.27 7.40 7.60 10.00 10.65 D 0.697 0.713 17.70 18.10 28 AE TES: D&E MITI DO NOT INCLUDE MOLD FLASH D FLASH OR PROTRUSIONS NOT MULD FLASH UR PRUTRUSIUNS NE TO EXCEED 15mm (.006*) LEADS TO BE COPLANAR WITHIN .02mm (.004*) З. .102mm (004*) 4. CONTROLLING DIMENSION: MILLIMETER 5. MEETS JEDEC MS013-XX AS SHOWN IN ABOVE TABLE 6. N = NUMBER OF PINS PACKAGE FAMILY DUTLINE: SDIC .300" 1/1 21-0042 A 888 ÊĤ at and in the MILLIMETERS MIN MAX 4.80 5.00 MAX 0.197 MIN MAX 1.35 1.75 N MS012 8 A 14 B IN 189 1.2 / 3.80 4.00 5.80 6.20 0.030 50 0.157 28 0.244 DE NOT INCLUDE MOLD FLASH D FLASH OR PROTRUSIONS NOT KCEED JSMO (006') DS TE DE CEPLANAR WITHIN NG (004') DEMCSION MILLIMETER TROLLING MSOI2-XX AS SHOWN NEDWER MSOI2-XX AS SHOWN NUMBER OF FINS D&E D MOLD TO EX LEADS 3. 4. 5. 6. PACKAGE FAMILY DUTLINE: SDIC .150° 1/1 21-0041 A

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